

Attorney Docket No. 042390.P5120D

capacitors, and inductors;
testing said plurality of cache memory devices on said interposer;
coupling said interposer to a substrate with the solder balls and coupling a
microprocessor to the substrate after said testing if said plurality of cache memory devices
pass said testing; and
not coupling said interposer to the substrate and not coupling the microprocessor
device to the interposer if said plurality of cache memory devices does not pass said testing.

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concluded
21. (Amended three times) The method of claim 19 wherein the interposer comprises
organic material.

22. (temporarily removed from consideration) (Amended once) The method of claim 19
wherein coupling at least one semiconductor die comprises a C4 process.

24. (temporarily removed from consideration) (Amended once) The method of claim 19
further comprising coupling a single chip carrier to the substrate.

25. (temporarily removed from consideration) (Amended once) The method of claim 19
wherein coupling at least one semiconductor die comprises coupling memory chips to the
interposer.

26. (Amended once) The method of claim 19, further comprising:
creating a plurality of contacts on the substrate; and